ALPHA & OMEGA
SEMICONDUCTOR

AOD492

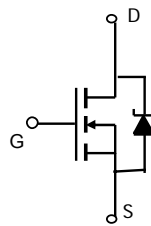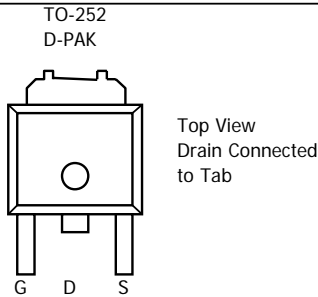# N-Channel Enhancement Mode Field Effect Transistor

SRFET ™

General Description

SRFET^{TM} AOD492 uses advanced trench technology with a monolithically integrated Schottky diode to provide excellent $R_{DS(ON)}$, and low gate charge. This device is suitable for use as a low side FET in SMPS, load switching and general purpose applications. S*tandard Product AOD492 is Pb-free (meets ROHS & Sony 259 specifications).*

Features

V_{DS} (V) = 30V
I_D =85A (V_{GS} = 10V)
$R_{DS(ON)}$ < 4.4mΩ (V_{GS} = 10V)
$R_{DS(ON)}$ < 6.2mΩ (V_{GS} = 4.5V)

UIS Tested!
Rg,Ciss,Coss,Crss Tested

TO-252
D-PAK

Top View
Drain Connected
to Tab

G D S

***SRFET*^{TM}**
Soft **R**ecovery MOS**FET**:
Integrated Schottky Diode

D

G

S

Absolute Maximum Ratings T$_A$=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current [B]	T$_C$=25°C [H]	I_D	85	A
	T$_C$=100°C		79	
Pulsed Drain Current[C]		I_{DM}	200	
Avalanche Current [C]		I_{AR}	30	A
Repetitive avalanche energy L=0.3mH [C]		E_{AR}	135	mJ
Power Dissipation [B]	T$_C$=25°C	P_D	100	W
	T$_C$=100°C		50	
Power Dissipation [A]	T$_A$=25°C	P_{DSM}	6.3	W
	T$_A$=70°C		4.0	
Junction and Storage Temperature Range		T$_J$, T$_{STG}$	-55 to 175	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	14	20	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		39	50	°C/W
Maximum Junction-to-Case [D]	Steady-State	$R_{\theta JC}$	0.8	1.5	°C/W

AOD492

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ	Max	Units
STATIC PARAMETERS							
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=1mA, V_{GS}=0V		30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V, V_{GS}=0V				0.1	mA
			T_J=125°C			20	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±20V				0.1	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ I_D=250μA		1.2	1.5	2.2	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V		200			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A			3.6	4.4	mΩ
			T_J=125°C		6.1	7.7	
		V_{GS}=4.5V, I_D=20A			5	6.2	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A			90		S
V_{SD}	Diode Forward Voltage	I_S=1A, V_{GS}=0V			0.36	0.5	V
I_S	Maximum Body-Diode + Schottky Diode Continuous Current [H]					85	A
DYNAMIC PARAMETERS							
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz			3760	4512	pF
C_{oss}	Output Capacitance				682		pF
C_{rss}	Reverse Transfer Capacitance				314		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz			0.75	1.5	Ω
SWITCHING PARAMETERS							
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=20A			62	74	nC
Q_g(4.5V)	Total Gate Charge				29	35	nC
Q_{gs}	Gate Source Charge				12		nC
Q_{gd}	Gate Drain Charge				12		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=0.75Ω, R_{GEN}=3Ω			9.5		ns
t_r	Turn-On Rise Time				8.5		ns
$t_{D(off)}$	Turn-Off DelayTime				34		ns
t_f	Turn-Off Fall Time				9		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, dI/dt=300A/μs			18	27	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, dI/dt=300A/μs			22		nC

A: The value of $R_{\theta JA}$ is measured with the device in a still air environment with T_A =25°C. The power dissipation P_{DSM} is based on $T_{J(MAX)}$=150°C, using t ≤ 10s junction-to-ambient thermal resistance.

B. The power dissipation P_D is based on $T_{J(MAX)}$=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=175°C.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 us pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175°C. The SOA curve provides a single pulse rating.

G. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.

H. The maximum current rating is limited by bond-wires.

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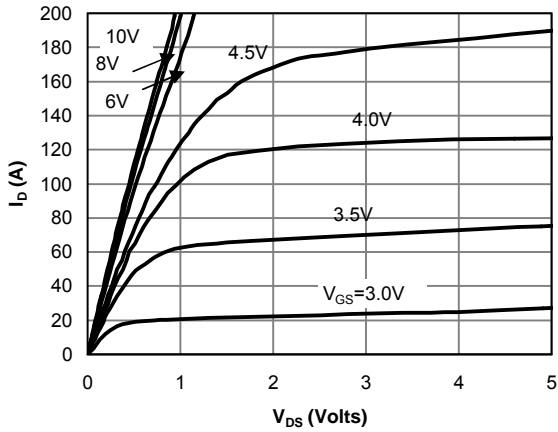## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
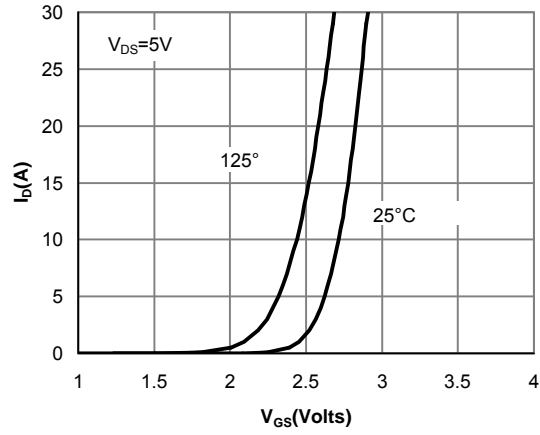

Figure 1: On-Region Characteristics

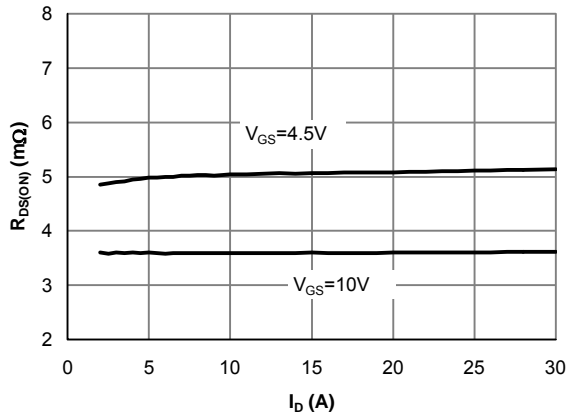**Figure 2: Transfer Characteristics**

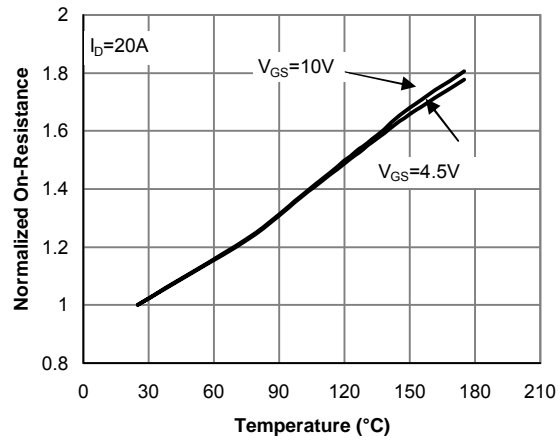**Figure 3: On-Resistance vs. Drain Current and Gate Voltage**
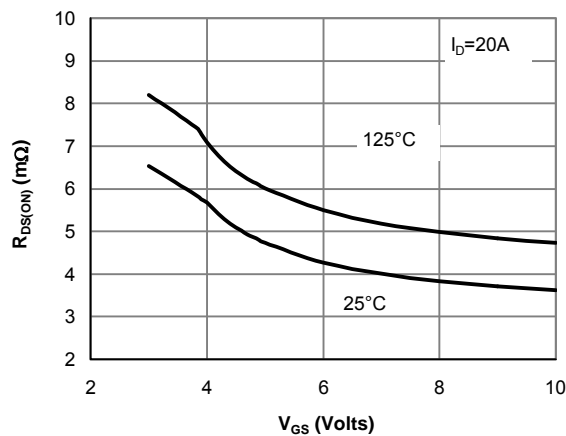

Figure 4: On-Resistance vs. Junction Temperature

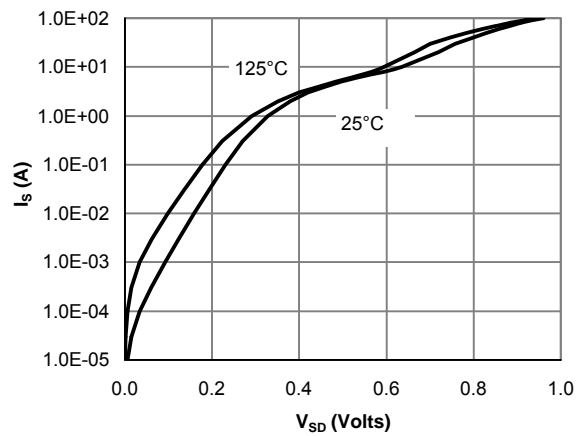**Figure 5: On-Resistance vs. Gate-Source Voltage**

Figure 6: Body-Diode Characteristics
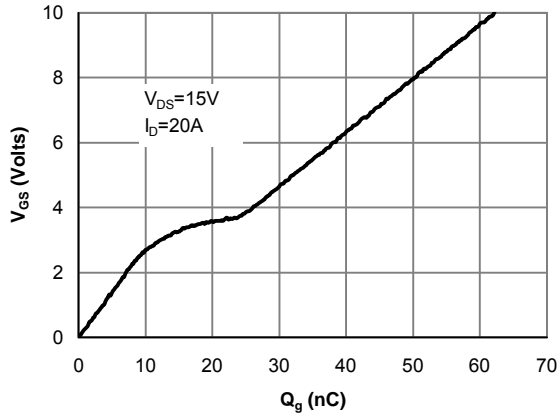
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
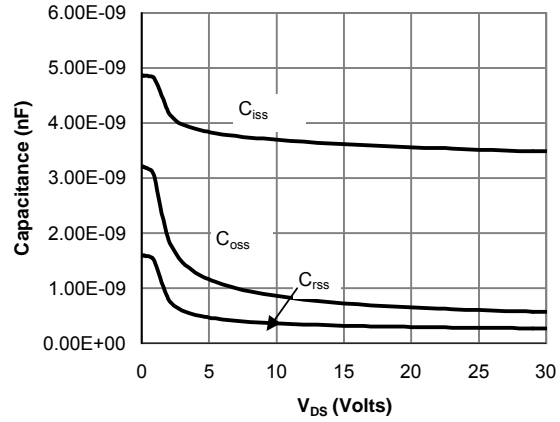

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics
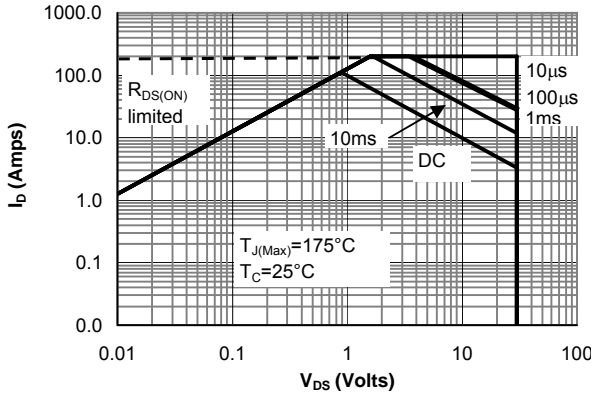
Figure 9: Maximum Forward Biased Safe Operating Area (Note F)
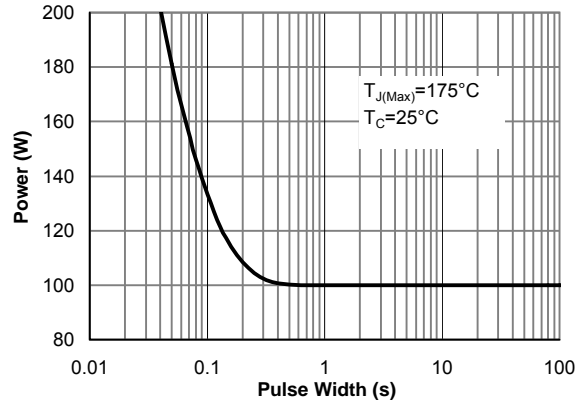
Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)
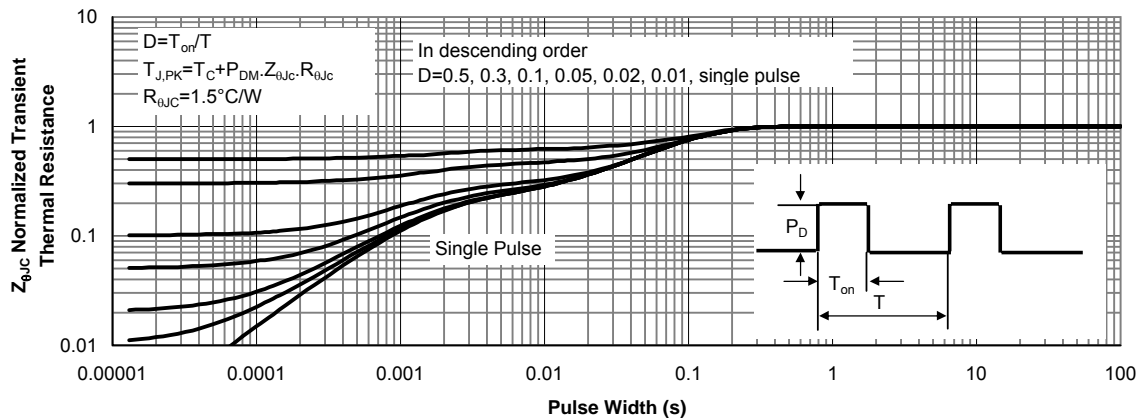
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

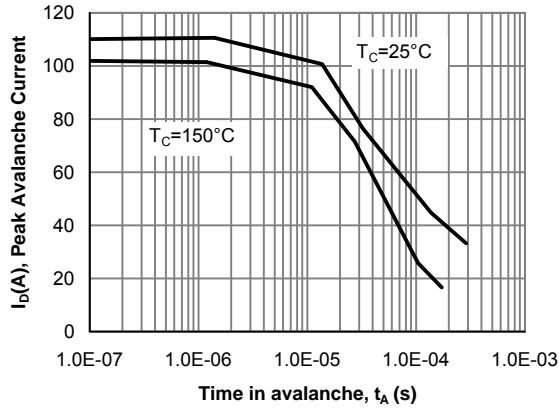## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
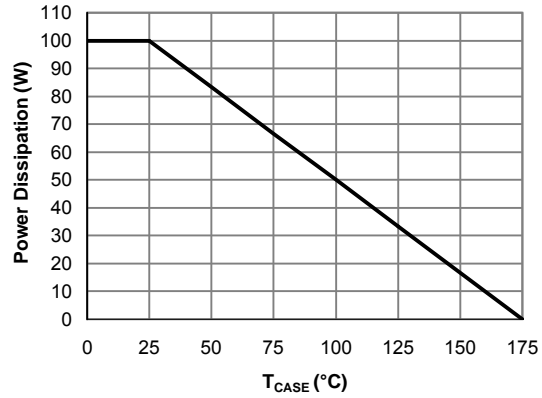

Figure 12: Single Pulse Avalanche capability
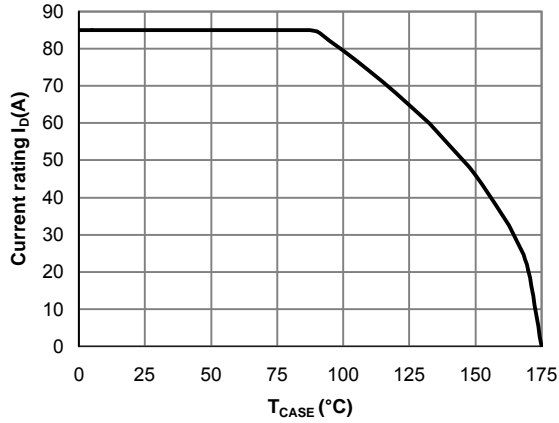

Figure 13: Power De-rating (Note B)

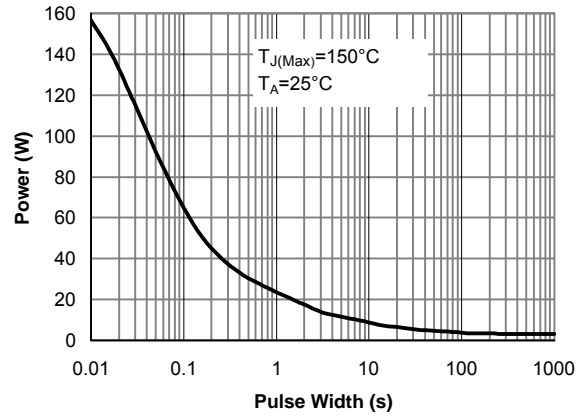Figure 14: Current De-rating (Note B)

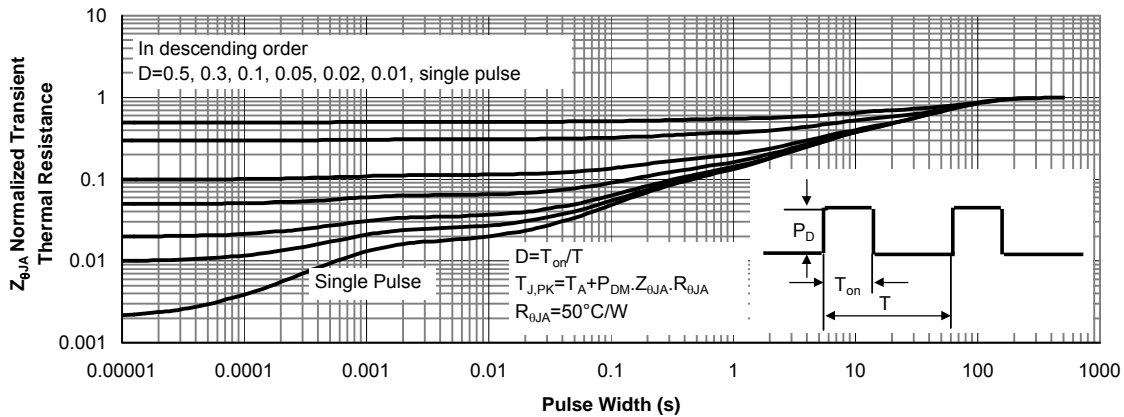Figure15: Single Pulse Power Rating Junction-to-Ambient (Note G)

Figure 16: Normalized Maximum Transient Thermal Impedance (Note G)